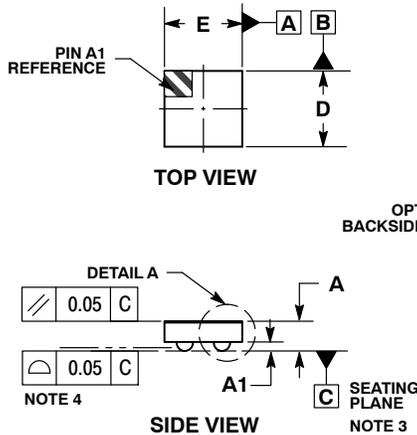




SCALE 4:1

WLCSP4, 0.84x0.86
CASE 567DC
ISSUE F

DATE 14 Jul 2016



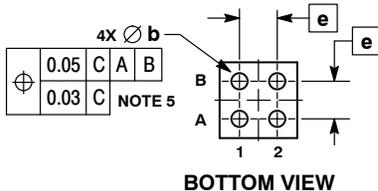
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.
 4. COPLANARITY APPLIES TO SPHERICAL CROWNS OF THE CONTACT BALLS.
 5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	---	---	0.38
A1	0.08	0.10	0.12
A2	0.23 REF		
A3	0.025 REF		
b	0.16	0.18	0.20
D	0.82	0.84	0.86
E	0.84	0.86	0.88
e	0.40 BSC		

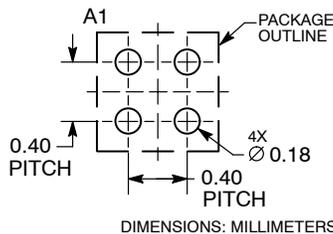
GENERIC MARKING DIAGRAM*



- X = Specific Device Code
- Y = Year
- M = Date Code



RECOMMENDED SOLDERING FOOTPRINT*



*This information is generic. Please refer to device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "▪", may or may not be present.

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP4, 0.84X0.86	PAGE 1 OF 1

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